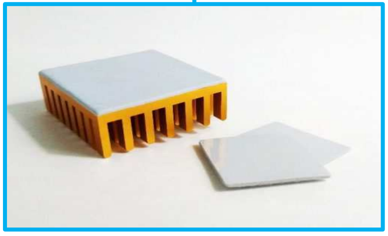
FT_TGF_030_R_NS_30

Thermal Pad

Our Thermal Foams also called Gap Pad or Gap Filler are non-siliconized thermo-conductive materials that solve the problems of heat dissipation. The TGF_030_R_NS is a mattress specially developed for applications where a low cooling requirement is required. Indeed, this one is a GOOD thermal conductor of 3W/mK, with a good thermal resistance thus facilitating the heat transfer and which also has an excellent electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

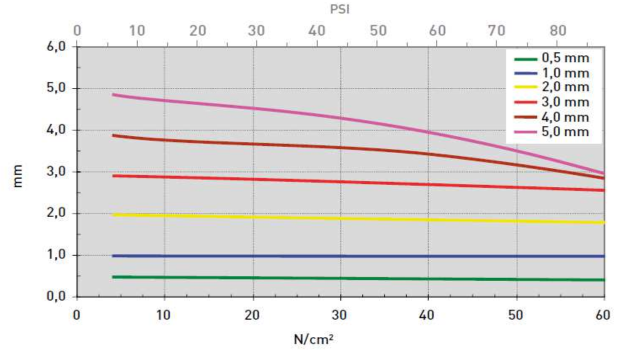


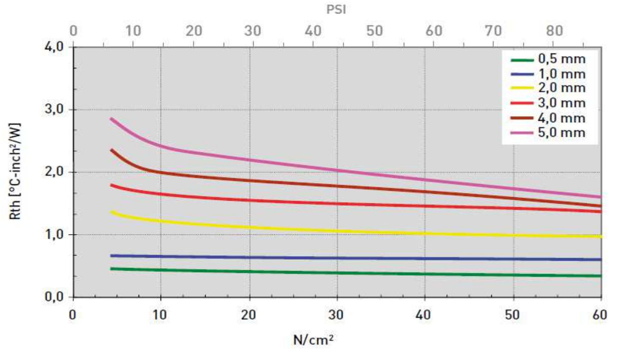
Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device,Wireless Hub, DDR ll Module, etc.

Technical characteristics

Features	Unit	TGF_030_R_NS			
Thickness	mm	0.5	1	2	3
Specific gravity	g/cm^3	2.9			
Color	-	White			
Hardness	Shore 00	70			
Size	mm	400*200			
Resistance @60 Psi	°C-inch²/W (mm)	0.38 (0.44)	0.63 (0.97)	1.03 (1.85)	1.47 (2.71)
Resistance @30 Psi		0.42 (0.46)	0.64 (0.98)	1.12 (1.85)	1.57 (2.81)
Resistance @10 Psi		0.45 (0.47)	0.65 (0.99)	1.25 (1.96)	1.72 (2.88)
Thermal conductivity	W/mK	3			
Temperature	°C	-40 to 130			
Breakdown voltage	kV/mm	7.8			
Volume resistance	0hm - cm	1 x 10^{11}			
Contante dielectric	@1MHz	-			

The TGF_030_R_NS is available in 0.5/1/2/3/4/5mm thicknesses.





Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user’s responsibility to perform their own tests to ensure that the product meets their needs.